TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130401005
Transfer of select devices in the Vertical Diode-BD process node to CFAB Facility
Change Notification / Sample Request

Date: 4/4/2013
To: MOUSER PCN

Dear Customer:

In January, 2012, TI announced plans to close two older 6-inch manufacturing facilities in Hiji, Japan and Houston, Texas. This product change announcement is to support transfer of products in the Vertical Diode-Bi-Directional process node from these wafer fabs to an alternate site. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days to ensure you can complete your evaluation and product transfer to the new site can be completed prior to the fab closure.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130401005
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPD1E10B06DPYR	null
TPD1E10B09DPYR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130401005	**PCN Date:**	04/04/2013

Title:	Transfer of select devices in the Vertical Diode-BD process node to CFAB Facility

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

Proposed 1st Ship Date:	07/04/2013	**Estimated Sample Availability:**	Date available upon sample request

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☒	Wafer Fab Process

PCN Details

Description of Change:

This change notification is to announce the transfer of select devices in the Vertical Diode – Bi-Directional process node from HIJI to the CFAB facility. This will also include a wafer diameter change from 6” to 8”.

Current	**New**
Site, process, wafer dia.	**Site, process, wafer dia.**
HIJI/ VD-BD, 150mm	**CFAB/ VD-BD, 200mm**

Reason for Change:

Continuity of Supply. HIJI site shutdown.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip site code (20L)	Chip country code (21L)
HIJI	HIJ	JPN

New

Chip Site	**Chip site code (20L)**	**Chip country code (21L)**
CFAB	**CU3**	**CHN**

Sample product shipping label (not actual product label)


TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750
G4
(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO :USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TPD1E10B06DPYR	TPD1E10B09DPYR	TPD1E6B06DPLR
TPD1E10B06DPYT	TPD1E10B09DPYT	TPD1E6B06DPLT

Qualification Plan:

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qualification Schedule:	**Start:**	03/2013	**End:**	End of 07/2013

Qual Vehicle: TPD4E101DPWR

Wafer Fab Site:	CFAB	Metallization:	AlCuTiW
Wafer Fab Process:	VD	Wafer Diameter:	200mm

Qualification: ☒ **Plan** ☐ **Test Results**

Reliability Test	Conditions	Sample Size/Fails Lot#1	 Lot#2	 Lot#3
Preconditioning	-	231/0	231/0	231/0
HTOL High Temp Op Life	150C (300 Hrs)	77/0	-	-
Electrical Characterization	-	30/0	30/0	30/0
High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cycles)	77/0	77/0	77/0
ESD CDM	500V	3/0	3/0	3/0
ESD HBM	1000V	3/0	3/0	3/0

**Preconditioning: Level 1-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com